

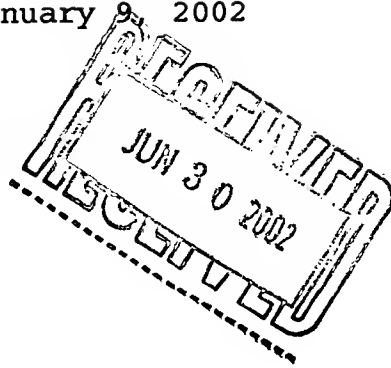


TSMC-00-863

January 9, 2002

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603



Subject:

Serial No. 09/998,787 10/31/01

Tien-I Bao, Jeng Shwang-Ming,  
Syun-Ming Jang, Chen-Hua Yu,  
Kuen-Chyr Lee

A SOLUTION TO THE PROBLEM OF COPPER  
HILLOCKS

Grp. Art Unit: 2812

RECEIVED  
FEB-6-2002  
TECHNOLOGY CENTER 2800

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner of Patents and  
Trademarks, Washington, D.C. 20231, on January 22, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

SB Ackerman 1/22/02

U.S. Patent 5,714,418 to Bai et al., "Diffusion Barrier for Electrical Interconnects in an Integrated Circuit," discloses a capping layer of nitride over copper, then an oxide layer.

U.S. Patent 5,612,254 to Mu et al., "Methods of Forming an Interconnect on a Semiconductor Substrate," discusses a silicon nitride layer over copper.

U.S. Patent 5,654,232 to Gardner, "Wetting Layer Sidewalls to Promote Copper Reflow into Grooves," teaches a copper damascene process.

U.S. Patent 5,589,233 to Law et al., "Single Chamber CVD Process for Thin Film Transistors," discloses a chamber pre-coat process.

Sincerely,

A handwritten signature in black ink, appearing to read "SBA", is written over the typed name.

Stephen B. Ackerman,  
Reg. No. 37761